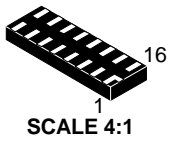


MECHANICAL CASE OUTLINE

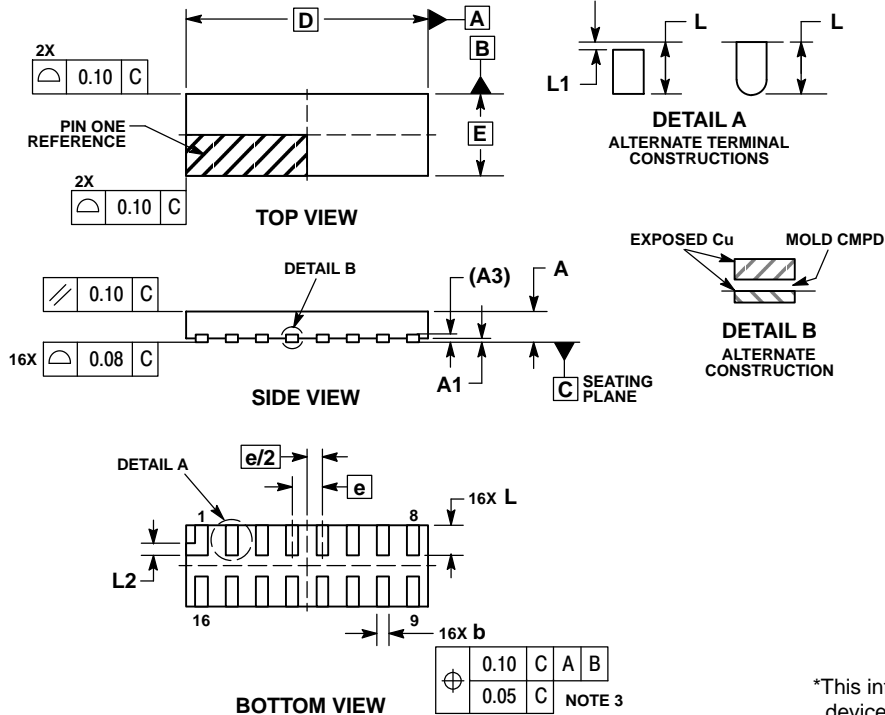
PACKAGE DIMENSIONS

ON Semiconductor®



XDFN16 4.0x1.35, 0.5P
CASE 711AZ
ISSUE O

DATE 09 SEP 2014



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.40	0.50
A1	0.00	0.05
A3	0.15 REF	
b	0.15	0.25
D	4.00 BSC	
E	1.35 BSC	
e	0.50 BSC	
L	0.40	0.60
L1	---	0.15
L2	0.20 REF	

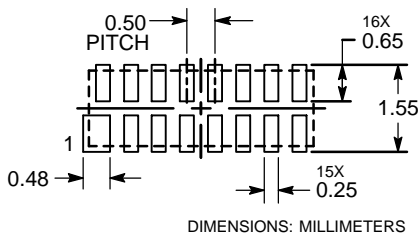
GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- M = Month Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	XDFN16 4.0X1.35, 0.5P	PAGE 1 OF 2

